

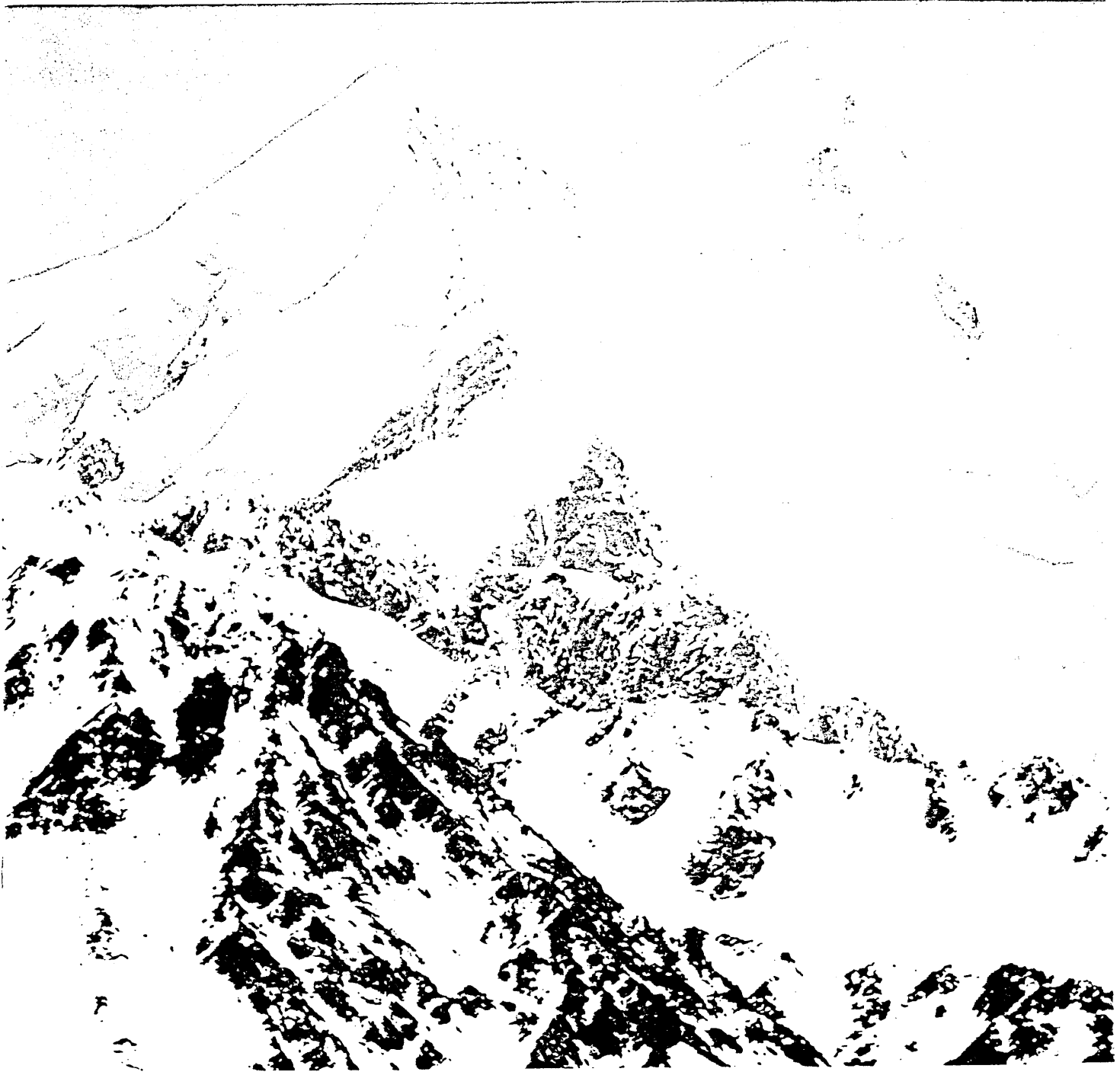
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170-082
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SHORT FORM CATALOG

HEAT SINKS AND DISSIPATORS

FOR SEMICONDUCTORS, INTEGRATED CIRCUITS AND MICROCOMPUTERS



A Complete Line of Heat Sinks/Dissipators for Transistors, Diodes, ICs and Microcircuits.

This short form catalog lists only our most popular devices. If you don't see the device which precisely meets your needs, chances are excellent that your local technical sales representative can recommend the exact part from our general catalog. See back cover for representatives and distributors in your area.

Various Standard Materials and Finishes

IERC products are available in a variety of hole patterns, mounting configurations, mate-

rials and finishes. Space does not permit listing ordering instructions for all these variations. Additional information is available from our staff of the engineering sales representatives.

Custom Designs

Tooling is already available for hundreds of variations of the standard products listed here, so many special requirements can be met without tooling charges. For special problems, IERC has a large staff of design and applica-

tions engineers to provide technical assistance.

Thermal data: The thermal resistance values listed in this short form catalog are intended to help an engineer select a suitable dissipator for a Natural-Convection application. For thermal and mechanical information on all of IERC's board-mounted dissipators refer to the IERC General Catalog.

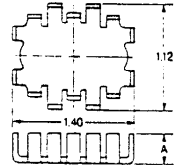
Dimension information: All dimensions contained in this short form catalog are for reference use only. Contact IERC for dimensions with tolerances and/or standard part drawings.

Heat dissipators for metal case, case-mounted semiconductors



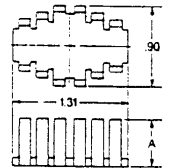
LB Series

Semiconductor Case Type	θ °C/W.	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-66	19.7	LB66B2U	LB66B2CB	LB66B2B	.31
TO-66	17.1	LB66B1U	LB66B1CB	LB66B1B	.50



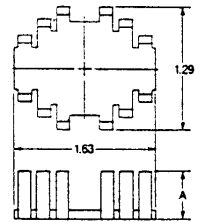
LA—A Series

Semiconductor Case Type	θ °C/W.	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-66	28.9	LAD66A1U	LAD66A1CB	LAD66A1B	.25
TO-66	19.7	LAD66A2U	LAD66A2CB	LAD66A2B	.50
TO-66	16.3	LAD66A3U	LAD66A3CB	LAD66A3B	.75
TO-66	14.4	LAD66A4U	LAD66A4CB	LAD66A4B	1.00



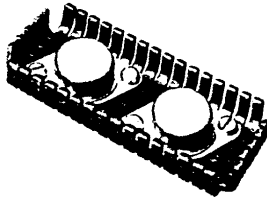
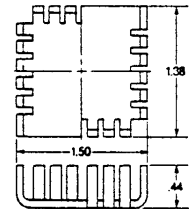
LA—B Series

TO-66	14.3	LAD66B2U	LAD66B2CB	LAD66B2B	.50
TO-66	12.1	LAD66B3U	LAD66B3CB	LAD66B3B	.75
TO-66	10.7	LAD66B4U	LAD66B4CB	LAD66B4B	1.00
TO-66	9.8	LAD66B5U	LAD66B5CB	LAD66B5B	1.25
TO-3	14.1	LATO3B2U	LATO3B2CB	LATO3B2B	.50
TO-3	12.0	LATO3B3U	LATO3B3CB	LATO3B3B	.75
TO-3	10.3	LATO3B4U	LATO3B4CB	LATO3B4B	1.00
TO-3	9.3	LATO3B5U	LATO3B5CB	LATO3B5B	1.25
Any TO-3	15.3	LA363B2U	LA363B2CB	LA363B2B	.50
Any TO-3	12.9	LA363B3U	LA363B3CB	LA363B3B	.75
Any TO-3	11.2	LA363B4U	LA363B4CB	LA363B4B	1.00
Any TO-3	10.0	LA363B5U	LA363B5CB	LA363B5B	1.25



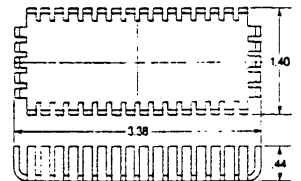
UP3 Series

Semiconductor Case Type	θ °C/W.	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-66	14.2	UP3-T066-U	UP3-T066-CB	UP3-T066-B
TO-3	13.6	UP3-T03-U	UP3-T03-CB	UP3-T03-B
Universal	—	UP3-425-U	UP3-425-CB	UP3-425-B



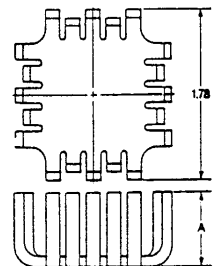
UP10 Series

Semiconductor Case Type	θ °C/W.	Part Number		
		Unplated	Comm'l. Black	Military Black
2 Ea. TO-3	7.7	UP10-T03-2U	UP10-T03-2CB	UP10-T03-2B
2 Ea. Universal	—	UP10-426-2U	UP10-426-2CB	UP10-426-2B
1 Ea. TO-3	8.7	UP10-T03-U	UP10-T03-CB	UP10-T03-B



UP, UP1 and UP2 Series

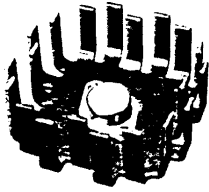
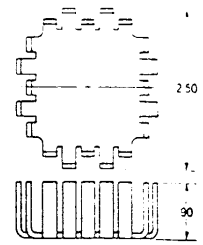
Semiconductor Case Type	θ °C/W.	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-66	11.5	UP1-T066-U	UP1-T066-CB	UP1-T066-B	.50
TO-66	9.6	UP2-T066-U	UP2-T066-CB	UP2-T066-B	.75
TO-66	7.9	UP-T066-U	UP-T066-CB	UP-T066-B	1.00
TO-3	10.4	UP1-T03-U	UP1-T03-CB	UP1-T03-B	.50
TO-3	8.3	UP2-T03-U	UP2-T03-CB	UP2-T03-B	.75
TO-3	7.1	UP-T03-U	UP-T03-CB	UP-T03-B	1.00
Universal	—	UP1-420-U	UP1-420-CB	UP1-420-B	.50
Universal	—	UP2-420-U	UP2-420-CB	UP2-420-B	.75
Universal	—	UP-420-U	UP-420-CB	UP-420-B	1.00





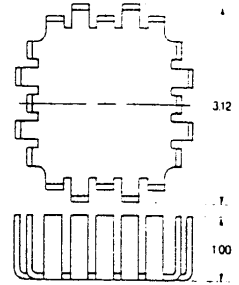
HP1 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-66	6.0	HP1-T066-U	HP1-T066-CB	HP1-T066-B
TO-3	5.4	HP1-T03-U	HP1-T03-CB	HP1-T03-B
Universal	—	HP1-420-U	HP1-420-CB	HP1-420-B

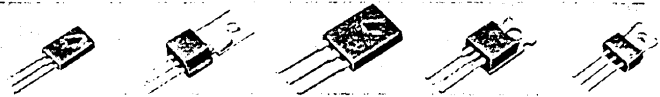


HP3 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-66	5.0	HP3-T066-U	HP3-T066-CB	HP3-T066-B
TO-3	4.4	HP3-T03-U	HP3-T03-CB	HP3-T03-B
Universal	—	HP3-420-U	HP3-420-CB	HP3-420-B

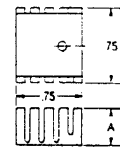


Heat dissipators for plastic case, lead-mounted semiconductors



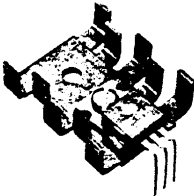
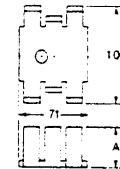
PC Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126/127/220	27.3	PC1-1U	PC1-1CB	PC1-1B	.38
TO-126/127/220	27.3	PC1-3U*	PC1-3CB	PC1-3B	.38
TO-126/127/220	22.0	PC4-1U	PC4-1CB	PC4-1B	.75
TO-126/127/220	22.0	PC4-3U*	PC4-3CB	PC4-3B	.75



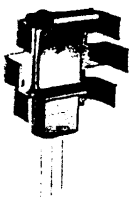
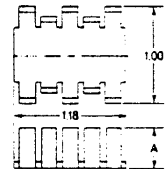
PA Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126/127/220	26.8	PA1-1U	PA1-1CB	PA1-1B	.50
TO-126/127/220	30.0	PA2-1U	PA2-1CB	PA2-1B	.31



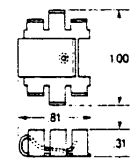
PB Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126/127/220	22.1	PB1-1U	PB1-1CB	PB1-1B	.50
Dual	—	PB1-2U	PB1-2CB	PB1-2B	.50
TO-126/127/220	25.0	PB2-1U	PB2-1CB	PB2-1B	.31
TO-126/127/220	—	PB2-2U	PB2-2CB	PB2-2B	.31



PSC2 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-202	42.9	PSC2-1U	PSC2-1CB	PSC2-1B
TO-220	41.7	PSC2-2U	PSC2-2CB	PSC2-2B
Mota. 152	46.9	PSC2-3U	PSC2-3CB	PSC2-3B
TO-126	45.5	PSC2-4U	PSC2-4CB	PSC2-4B
TO-127	37.5	PSC2-5U	PSC2-5CB	PSC2-5B

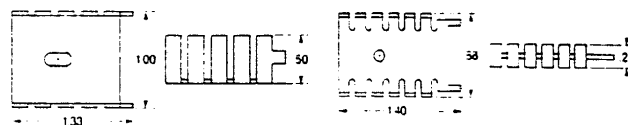
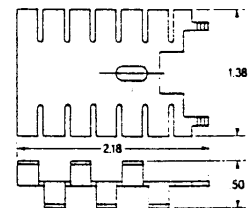


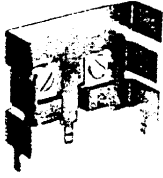
Vertically mounted heat dissipators with board-mounting tabs



Vertical Tab Mounted Dissipators

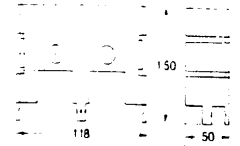
Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-126/127/220	20.0	PB1-36U	PB1-36CB	PB1-36B
TO-126/127/220	25.9	PSB2-1U	PSB2-1CB	PSB2-1B
TO-202	17.6	PSD1-1U	PSD1-1CB	PSD1-1B
TO-126/127/220	14.4	PSD1-2U	PSD1-2CB	PSD1-2B





PSE1 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
Mota. 152	17.1	PSE1-1U	PSE1-1CB	PSE1-1B
TO-126/127/220	15.0	PSE1-2U	PSE1-2CB	PSE1-2B
TO-202	17.4	PSE1-3U	PSE1-3CB	PSE1-3B

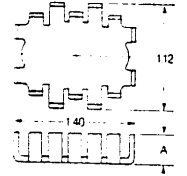


Board-mounted heat dissipators



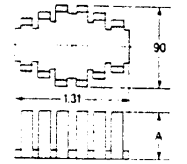
LB Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126/127/220	16.5	LB6681U	LB6681CB	LB6681B	.50
TO-126/127/220	20.8	LB6682U	LB6682CB	LB6682B	.31



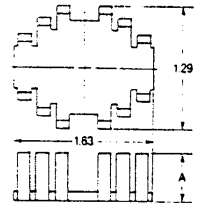
LA-A Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126/127/220	25.0	LA666A1U	LA666A1CB	LA666A1B	.25
TO-126/127/220	20.0	LA666A2U	LA666A2CB	LA666A2B	.50
TO-126/127/220	17.0	LA666A3U	LA666A3CB	LA666A3B	.75
TO-126/127/220	14.7	LA666A4U	LA666A4CB	LA666A4B	1.00



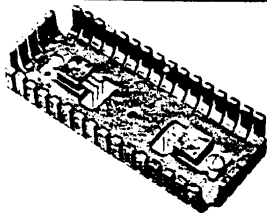
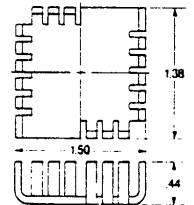
LA-B Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126	15.0	LAT012682U	LAT012682CB	LAT012682B	.50
TO-126	12.9	LAT012683U	LAT012683CB	LAT012683B	.75
TO-126	11.4	LAT012684U	LAT012684CB	LAT012684B	1.00
TO-126	9.7	LAT012685U	LAT012685CB	LAT012685B	1.25
TO-127/220	15.0	LAT012782U	LAT012782CB	LAT012782B	.50
TO-127/220	12.9	LAT012783U	LAT012783CB	LAT012783B	.75
TO-127/220	11.4	LAT012784U	LAT012784CB	LAT012784B	1.00
TO-127/220	9.7	LAT012785U	LAT012785CB	LAT012785B	1.25
Universal	—	LA39482U	LA39482CB	LA39482B	.50
Hole Pattern	—	LA39483U	LA39483CB	LA39483B	.75
	—	LA39484U	LA39484CB	LA39484B	1.00
	—	LA39485U	LA39485CB	LA39485B	1.25



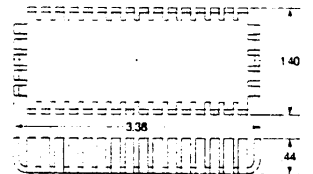
UP3 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-126	15.0	UP3-T0126-U	UP3-T0126-CB	UP3-T0126-B
TO-127/220	15.0	UP3-T0127-U	UP3-T0127-CB	UP3-T0127-B
Universal	—	UP3-425-U	UP3-425-CB	UP3-425-B
2 Ea. TO-126/127/220	13.6	UP3-456-U	UP3-456-CB	UP3-456-B



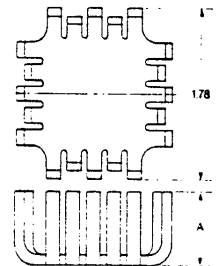
UP10 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
2 Ea. TO-126/127/220	7.5	UP10-T0127-U	UP10-T0127-CB	UP10-T0127-B
Universal	N.A.	UP10-426-2U	UP10-426-2CB	UP10-426-2B



UP, UP1, UP2 Series

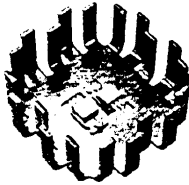
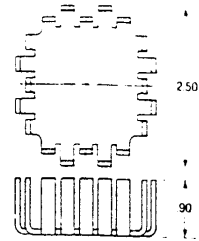
Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Unplated	Comm'l. Black	Military Black	
TO-126	11.7	UP1-T0126-U	UP1-T0126-CB	UP1-T0126-B	.50
TO-126	9.4	UP2-T0126-U	UP2-T0126-CB	UP2-T0126-B	.75
TO-126	8.2	UP-T0126-U	UP-T0126-CB	UP-T0126-B	1.00
TO-127/220	11.7	UP1-T0127-U	UP1-T0127-CB	UP1-T0127-B	.50
TO-127/220	9.4	UP2-T0127-U	UP2-T0127-CB	UP2-T0127-B	.75
TO-127/220	8.2	UP-T0127-U	UP-T0127-CB	UP-T0127-B	1.00
2 Ea. TO-126 or	10.7	UP1-T0127-2U	UP1-T0127-2CB	UP1-T0127-2B	.50
2 Ea. TO-127 or	8.3	UP2-T0127-2U	UP2-T0127-2CB	UP2-T0127-2B	.75
2 Ea. TO-220	7.4	UP-T0127-2U	UP-T0127-2CB	UP-T0127-2B	1.00





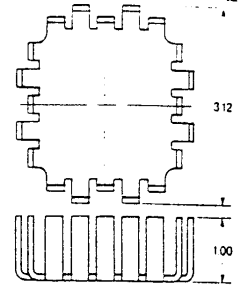
HP1 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-126	6.5	HP1-TO126-U	HP1-TO126-CB	HP1-TO126-B
TO-127/220	6.5	HP1-TO127-U	HP1-TO127-CB	HP1-TO127-B
Dual TO-127/220	5.6	HP1-TO127-4U	HP1-TO127-4CB	HP1-TO127-4B

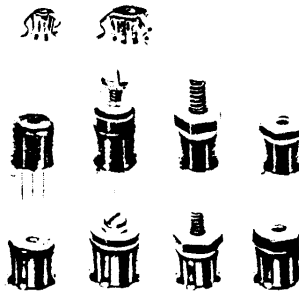


HP3 Series

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
TO-126	5.0	HP3-TO126-U	HP3-TO126-CB	HP3-TO126-B
TO-127/220	5.0	HP3-TO127-U	HP3-TO127-CB	HP3-TO127-B
2 Ea. TO-127/220	4.0	HP3-TO127-4U	HP3-TO127-4CB	HP3-TO127-4B
4 Ea. TO-127/220	3.7	HP3-319-U	HP3-319-CB	HP3-319-B

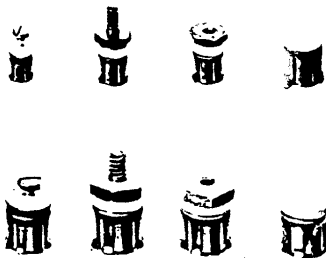


Heat dissipators for metal case, case-mounted semiconductors



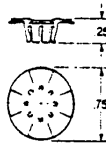
Thermal Link Retainers Without BeO Insulators

Semiconductor Case Type	Part Number with Black Cadmium Finish	Part Number with Dull Nickel Finish	Part Number with Insulube Finish	Mounting Method	"A" Dim.	"B" Dim.
TO-18	TXBC-019-023B	TXBC-019-023ND	TXBC-019-023	Spring Clip	.23	.43
TO-5	TXBC-032-025B	TXBC-032-025ND	TXBC-032-025	Spring Clip	.25	.56
TO-18	TXBE-019-021B	TXBE-019-021ND	TXBE-019-021	Rivet/Solder	.21	.22
TO-5	TXBE-032-031B	TXBE-032-031ND	TXBE-032-031	Rivet/Solder	.31	.37
TO-18	TXB2P-019-028B	TXB2P-019-028ND	TXB2P-019-028	2-56 Screw	.28	.22
TO-5	TXB2P-032-037B	TXB2P-032-037ND	TXB2P-032-037	4-40 Screw	.37	.37
TO-18	TX1807B	TX1807ND	TX1807	4-40 Stud	.50	.25
TO-18	TX1807-1B	TX1807-1ND	TX1807-1	6-32 Stud	.50	.25
TO-5	TX0507-1B	TX0507-1ND	TX0507-1	6-32 Stud	.59	.37
TO-5	TX0507-2B	TX0507-2ND	TX0507-2	10-32 Stud	.59	.37
TO-18	TX1847B	TX1847ND	TX1847	2-56 Hex Nut	.28	.25
TO-5	TX0547B	TX0547ND	TX0547	4-40 Hex Nut	.41	.37



Thermal Link Retainers With BeO Insulators

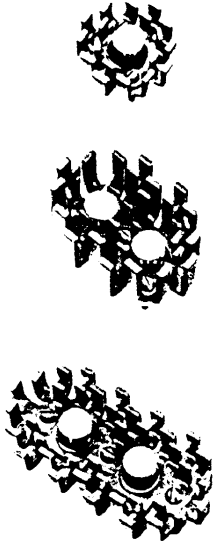
Semiconductor Case Type	Part Number with Black Cadmium Finish	Part Number with Dull Nickel Finish	Part Number with Insulube Finish	Mounting Method	"A" Dim.	"B" Dim.
TO-18	TXP1803B	TXP1803ND	TXP1803	2-56 Screw	.34	.22
TO-18	TXP1808B	TXP1808ND	TXP1808	2-56 Screw	.34	.22
TO-5	TXP0503B	TXP0503ND	TXP0503	4-40 Screw	.43	.38
TO-5	TXP0508B	TXP0508ND	TXP0508	4-40 Screw	.43	.38
TO-18	—	TX1805-ND	—	Solder	.27	.22
TO-5	—	TX0505-ND	—	Solder	.37	.30
TO-18	TX1806B	TX1806ND	—	4-40 Stud	.56	.25
TO-18	TX1806-1B	TX1806-1ND	—	6-32 Stud	.56	.25
TO-5	TX0506-1B	TX0506-1ND	—	6-32 Stud	.65	.38
TO-5	TX0506-2B	TX0506-2ND	—	10-32 Stud	.65	.38
TO-18	TX1822B	TX1822ND	—	2-56 Hex Nut	.34	.25
TO-5	TX0522B	TX0522ND	—	4-40 Hex Nut	.47	.38



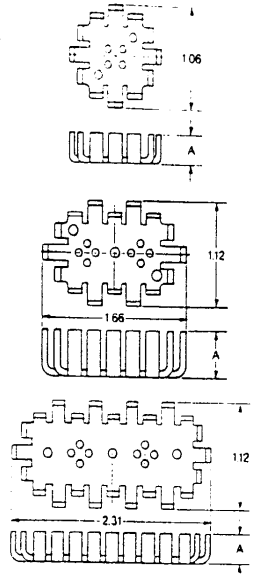
Fan Tops

Semiconductor Case Type	θ °C/W	Part Number			Material	"A" Dim.	"B" Dim.
		Unplated	Black Cadmium	Black Chem.			
TO-18	150.0	TXBF-019-025U	TXBF-019-025B	N.A.	Be Cu	.25	.50
TO-18	150.0	TXCF-019-025U	N.A.	TXCF-019-025CB	Brass	.25	.50
TO-5	81.1	TXBF-032-025U	TXBF-032-025B	N.A.	Be Cu	.25	.75
TO-5	81.1	TXCF-032-025U	N.A.	TXCF-032-025CB	Brass	.25	.75
TO-5	57.7	TXBF2-032-036U	TXBF2-032-036B	N.A.	Brass Fan Be Cu Retainer	.33	1.25

LP Series



Semiconductor Case Type	θ °C/W	Part Number				"A" Dim.
		Unplated	Comm'l Black	Military Black	Insulube 448 [®]	
One TO-18	33.0	LP18A1U	LP18A1WCB	LP18A1B	LP18A1	50
One TO-18	38.9	LP18A2U	LP18A2WCB	LP18A2B	LP18A2	31
Two TO-18s	27.0	LP18A3U	LP18A3WCB	LP18A3B	LP18A3	50
Two TO-18s	32.0	LP18A4U	LP18A4WCB	LP18A4B	LP18A4	31
One TO-5	23.1	LP5A1U	LP5A1WCB	LP5A1B	LP5A1	50
One TO-5	24.2	LP5A2U	LP5A2WCB	LP5A2B	LP5A2	31
One TO-5	16.3	LP5B1U	LP5B1WCB	LP5B1B	LP5B1	50
One TO-5	19.7	LP5B2U	LP5B2WCB	LP5B2B	LP5B2	31
Two TO-5s	15.6	LP5B3U	LP5B3WCB	LP5B3B	LP5B3	50
Two TO-5s	20.8	LP5B4U	LP5B4WCB	LP5B4B	LP5B4	31
One TO-5	12.6	LP5C1U	LP5C1WCB	LP5C1B	LP5C1	50
One TO-5	15.6	LP5C2U	LP5C2WCB	LP5C2B	LP5C2	31
Two TO-5s	12.1	LP5C3U	LP5C3WCB	LP5C3B	LP5C3	50
Two TO-5s	15.0	LP5C4U	LP5C4WCB	LP5C4B	LP5C4	31



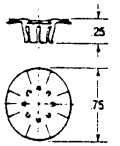
Heat dissipators for plastic case, case-mounted semiconductors



Fan Tops



Semiconductor Case Type	θ °C/W	Part Number			Material	"A" Dim.	"B" Dim.
		Unplated	Black Coating	Black Cadmium			
R110 or R97a	150	TXCF-019-025U	TXCF-019-025CB	TXCF-019-025B	Brass	.25	.50
R110a or R97	—	TXCF-032-025U	TXCF-032-025CB	TXCF-032-025B	Brass	.25	.75
TO-92	153	TXC20U	TXC20CB	TXC20B	Brass	.25	.50
R110 or 97a	150	TXBF-019-025U	TXBF-019-025CB	TXBF-019-025B	Be Cu	.25	.50
R110a or R97	—	TXBF-032-025U	TXBF-032-025CB	TXBF-032-025B	Be Cu	.25	.75
TO-92	153	TX20U	TX20CB	TX20B	Be Cu	.25	.50

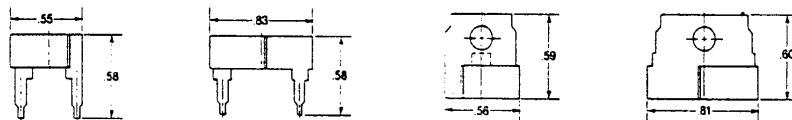


Universal "D" Series and Freestanding "D" Series



	Semiconductor Case Type	θ °C/W	Part Number			Material
			Unplated	Black Coating	Black Cadmium	
Universal "D"	One TO-92	146.8	RU671U	RU671CB	RU671B	Be Cu
	Two TO-92s	87.2	RU672U	RU672CB	RU672B	Be Cu
Freestanding "D"	One TO-92	140.4	RUR671U	RUR671CB	RUR671B	Be Cu
	Two TO-92s	74.3	RUR672U	RUR672CB	RUR672B	Be Cu

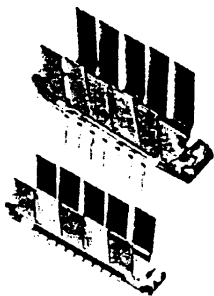
Note: Dissipators listed above are made from Beryllium Copper; they are also available in Brass, contact IERC for Part Numbers.



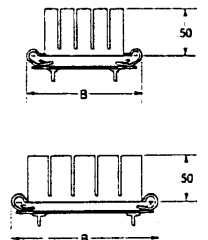
Heat dissipators for DIPs



PEP50AB, PEP50BB



Semiconductor Case Type	θ °C/W	Part Number		Material	"B" Dim.
		Assembly Part Number	Component Part Numbers		
.300 Wide DIP 14-16 Pins	23.8	PEP50AB	Dissipator PED50AB	Be Cu	1.30
			Conduction Bar PEC1AT/0120	Copper	
.300 Wide DIP 14-24 Pins	20.8	PEP50BB	Dissipator PED50BB	Be Cu	1.70
			Conduction Bar PEC1BT/0160	Copper	

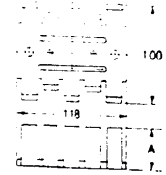




PB-10 Series

Semiconductor Case Type	θ °C/W	Part Number				"A" Dim.
		Unplated	Comm'l. Black	Military Black*	Insulube 448*	
.300 Wide DIPs with up to 16 Pins	27.8	PB1-10U	PB1-10CB	PB1-10B	PB1-10	50
	30.3	PB2-10U	PB2-10CB	PB2-10B	PB2-10	37

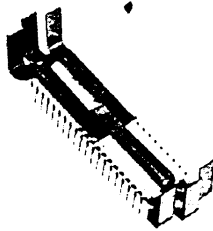
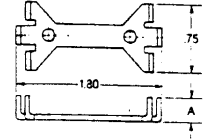
Note: Retainer, DC000080-2 required and must be ordered separately.



LIC Series

Semiconductor Case Type	θ °C/W	Part Number			"A" Dim.
		Comm'l. Black	Military Black*	Insulube 448*	
.300 Wide DIPs	28.9	LIC214A1WCB	LIC214A1B	LIC214A1	25
	26.3	LIC214A2WCB	LIC214A2B	LIC214A2	50
less than .700 long	23.7	LIC214A3WCB	LIC214A3B	LIC214A3	75
	22.2	LIC214A4WCB	LIC214A4B	LIC214A4	1.00

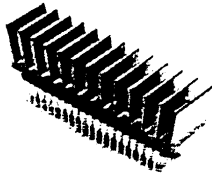
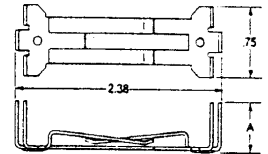
*Dissipator edges adjacent to the DIP pins are coated with an insulating compound.
Note: DC000080-2 retainer is required and must be ordered separately.



Micro Clip Dissipators

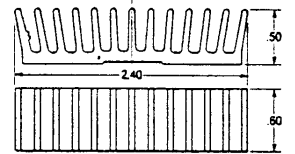
Semiconductor Case Type	θ °C/W	Part Number				"A" Dim.
		Unplated	Comm'l. Black	Military Black	Insulube 448*	
.600 Wide DIPs with 24-40 Pins	25.9	APIC025U	APIC025CB	APIC025B	APIC025	25
	22.9	APIC050U	APIC050CB	APIC050B	APIC050	50
	22.7	APIC075U	APIC075CB	APIC075B	APIC075	75

Note: APIC Dissipators are a two-piece assembly.



Extruded Dissipator for 40 Pin DIPs

Semiconductor Case Type	θ °C/W	Part Number		
		Unplated	Comm'l. Black	Military Black
.600 Wide 40 Pin DIPs	15.5	E155-001U	E155-001CB	E155-001B



Extruded Heat Dissipators for High-Power Semiconductors — Available in all popular configurations, or customized to meet your specific needs.

IERC manufactures an extensive line of extruded heat dissipators — more than 80 standard shapes. Extruded heat dissipators are particularly useful for applications where high power levels are encountered.

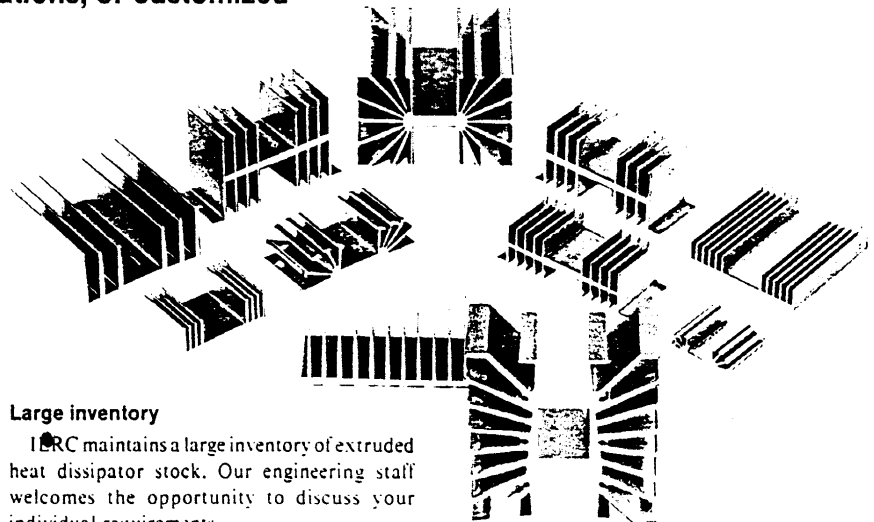
Customized for specific needs

To provide special assistance in meeting your thermal packaging requirement, IERC will:

- Cut to length
- Drill, punch, tap or notch holes as required
- Perform special machining on any IERC configuration to your specification
- Apply finishes to your requirements

Large inventory

IERC maintains a large inventory of extruded heat dissipator stock. Our engineering staff welcomes the opportunity to discuss your individual requirements.



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This reference document is the most comprehensive listing of heat dissipator products and performance information available today!

In addition to the highly accurate data available on the characteristics of each dissipator, there is an excellent discussion on the "Principles of Thermal Management" and tips on heat sink/dissipator applications.

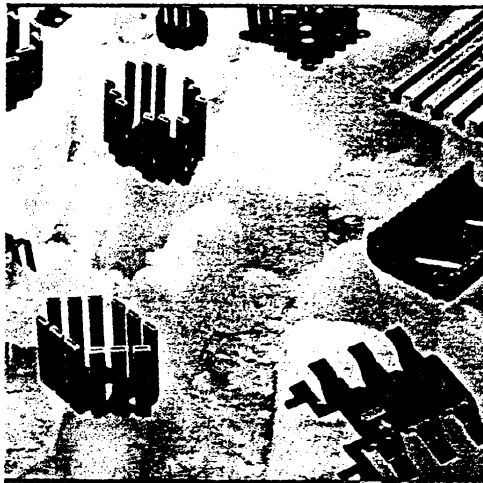
Products included in the catalog:

- Heat Dissipators for metal case, plastic case, case mounted and lead mounted semiconductors.
- Heat Dissipators for DIPs, flatpacks, and micro circuits.
- Extruded heat sinks for high power semiconductors.
- Thermal packaging components.

To facilitate each selection, all heat dissipator products are indexed by thermal resistance and by board area requirements. In addition, we have over 500 hole patterns available to accommodate virtually any semiconductor, and highly accurate heat dissipator performance curves for both natural convection and forced air.



HEAT SINK/DISSIPATOR PRODUCTS AND THERMAL MANAGEMENT GUIDE



Call the IERC Technical Representative nearest you and ask for your copy.



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